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# BLUETOOTH & 2.4 GHz WLAN GaAs MMIC TRANSCEIVER

#### Typical Applications

Transmit & Receive Switch for 2.4 GHz Applications:

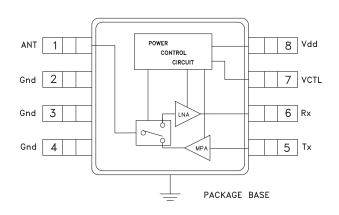
- Bluetooth
- HomeRF
- WLAN Radios

#### **Features**

Tx Gain: 15 dB, Rx Gain: 13 dB
Tx 1 dB Compression Point: 5 dBm
Rx Noise Figure: 3 dB @ 2.4 GHz

Single Positive Supply: +3V No External Matching Required

#### **Functional Diagram**



#### **General Description**

The HMC310MS8G & HMC310MS8GE are multifunction RFICs that incorporates a power amplifier (PA) and low noise amplifier (LNA) with a transmit/receive switch. These RFICs offer 15 dB gain and +5 dBm P1dB in the transmit mode and 13 dB of gain with an overall noise figure of 3 dB when in receive mode. Transmit and receive performance levels have been selected to meet the BLUETOOTH Class 2 & 3 requirements when used in conjunction with 2.4 GHz ASICs such as National Semiconductor's LMX3162. This low current and low cost transceiver requires no external circuitry to operate the amplifier power down features, and is available in the industry standard MSOP8G package, which is 0.118" x 0.190" (3.0mm x 4.9mm).

# Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vdd = +3V

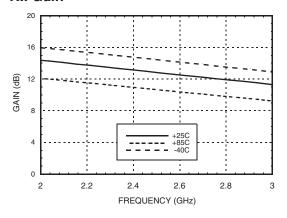
Parameter	Receive Mode			Transmit Mode			11.2
	Min.	Rx Тур.	Max.	Min.	Тх Тур.	Max.	Units
Frequency Range	2.4 - 2.5		2.4 - 2.5			GHz	
Gain	8	13	15	12	15	17	dB
Gain Variation over Temperature		0.03	0.04		0.03	0.04	dB/°C
Noise Figure		3.0	4.0				dB
Input Return Loss	4	6		4	7		dB
Output Return Loss	9	12		10	13		dB
Output Power for 1 dB Compression (P1dB)	-7	-4		1	5		dBm
Saturated Output Power (Psat)	-5	0		3	7		dBm
Output Third Order Intercept (IP3)	3	6		3	10		dBm
Supply Current (Idd)		12			24		mA



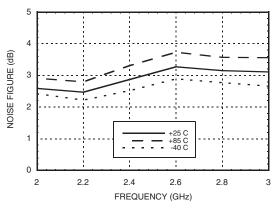
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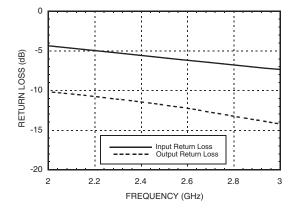
#### Rx Gain



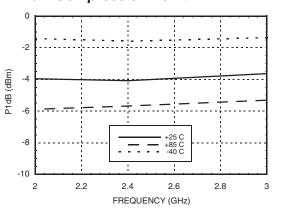
#### **Rx Noise Figure**



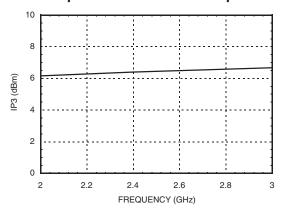
#### **Rx Return Loss**



#### **Rx 1dB Compression Point**



#### **Rx Output Third Order Intercept Point**

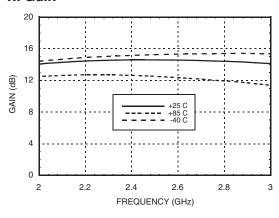




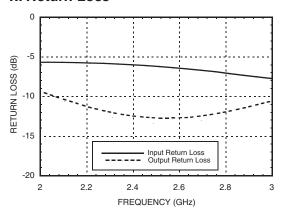
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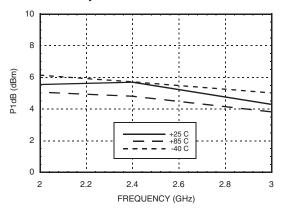
#### Tx Gain



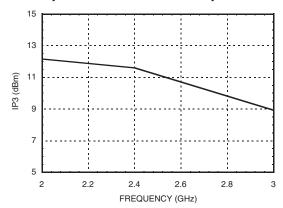
#### **Tx Return Loss**



#### **Tx 1dB Compression Point**



#### Tx Output Third Order Intercept Point





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#### **Absolute Maximum Ratings**

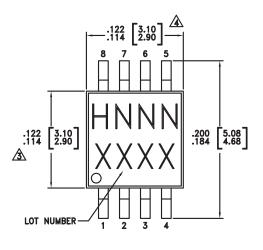
Drain Bias Voltage (Vdd)	+7.0 Vdc
Control Voltage Range (Vctl)	-0.2 to Vdd
RF Input Power (Vdd = +3.0 Vdc)	0 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 5 mW/°C above 85 °C)	0.325 W
Thermal Resistance (channel to ground paddle)	200 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

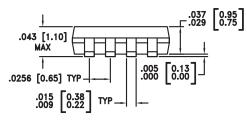
#### **Truth Table**

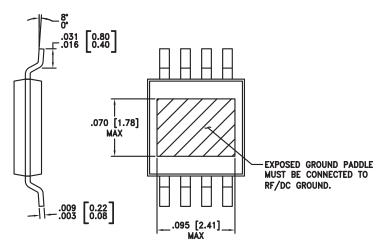
Tx Section Active	VCTL = Vdd
Rx Section Active	VCTL = 0V



### **Outline Drawing**







#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

#### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC310MS8G	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H310 XXXX
HMC310MS8GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	<u>H310</u> XXXX

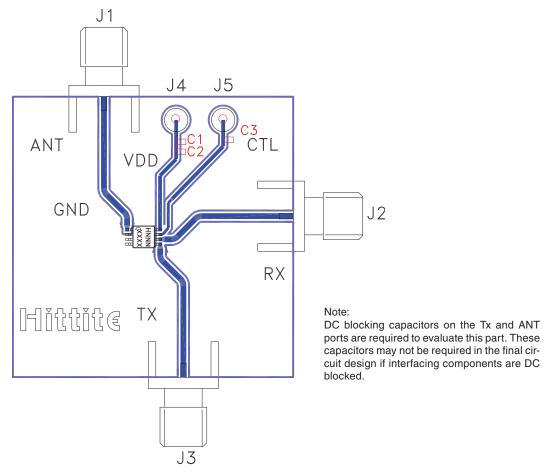
- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX



## BLUETOOTH & 2.4 GHz WLAN GaAs MMIC TRANSCEIVER



#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 103339 [1]

Item	Description	
J1, J2, J3	PCB Mount SMA Connector	
J4, J5	DC Pins	
C1	.01 μF Capacitor, 0603 Pkg.	
C2, C3	100 pF Capacitor, 0603 Pkg.	
U1	HMC310MS8G / HMC310MS8GE Transceiver	
PCB [2]	Evaluation Board 1.5" x 1.55"	

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



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Notes: